L	Hits	Search Text	DB	Time stamp
Number	3	nollot and (Called or Callian add average	USPAT;	2003/07/25
	3	pellet and (GaAsP or Gallium adj arsenic adj phosphorus)adj mixed adj crystal	EPO; JPO; DERWENT	10:51
-	7	(light adj emitting adj diode or LED) and (GaAsP or Gallium adj arsenic adj	USPAT; EPO; JPO;	2003/07/25 10:57
-	0	phosphorus)adj mixed adj crystal ((light adj emitting adj diode or LED)	DERWENT USPAT;	2003/07/25
		and (GaAsP or Gallium adj arsenide adj phosphide)adj3 mixed adj crystal) and raugh\$3 adj surface	EPO; JPO; DERWENT	10:58
_	1	((light adj emitting adj diode or LED) and (GaAsP or Gallium adj arsenide adj	USPAT; EPO; JPO;	2003/07/25
_	1	phosphide)adj3 mixed adj crystal) and rough\$3 adj surface (light adj emitting adj diode or LED) and	DERWENT USPAT;	2003/07/25
		(GaAsP or Gallium adj arsenide adj phosphide)adj3 mixed adj crystal and rough\$3 adj3 surface	EPO; JPO; DERWENT	10:59
_	2	(light adj emitting adj diode or LED) and (GaAsP or Gallium adj arsenide adj phosphide) adj3 mixed adj crystal and rough\$3 with surface	USPAT; EPO; JPO; DERWENT	2003/07/25 10:59
-	26	(light adj emitting adj diode or LED) and (GaAsP or Gallium adj arsenide adj	USPAT; EPO; JPO;	2003/07/25
-	0	phosphide)adj3 mixed adj crystal solder adj20 bump adj20 reliability and ((under adj ball adj metal) or UBM) and	DERWENT USPAT; EPO; JPO;	2003/09/01 17:18
		passivation adj20 layer and reflow\$3 and ((T adj shape\$d) or "T-shaped") and contact adj20 pad	DERWENT	
_	0	solder adj20 bump and ((under adj ball adj metal) or UBM) and passivation adj20 layer and reflow\$3 and ((T adj shape\$d) or "T-shaped") and contact adj20 pad	USPAT; EPO; JPO; DERWENT	2003/09/01
_	0	solder adj20 bump and ((under adj ball adj metal) or UBM) and passivation adj20 layer and reflow\$3 and ((T adj shape\$1)	USPAT; EPO; JPO; DERWENT	2003/09/01 17:19
_	0	or "T-shaped") and contact adj20 pad solder adj20 bump and (under adj ball adj metal or UBM) and passivation adj20 layer and reflow\$3 and (T adj shape\$1 or	USPAT; EPO; JPO; DERWENT	2003/09/01 17:19
_	0	"T-shaped") and contact adj20 pad solder adj20 bump and (under adj ball adj metal or UBM) and passivation adj20 layer	USPAT; EPO; JPO;	2003/09/01 17:20
	0	and reflow\$3 and (T adj shape\$1 or T-shaped) and contact adj20 pad solder adj20 bump and under adj ball adj	DERWENT USPAT;	2003/09/01
		metal and passivation adj20 layer and reflow\$3 and (T adj shape\$1 or T-shaped) and contact adj20 pad	EPO; JPO; DERWENT	17:20
-	0	solder adj20 bump and under adj ball adj metal and passivation adj20 layer and reflow\$3 and contact adj20 pad	USPAT; EPO; JPO;	2003/09/01 17:21
_	0	solder adj20 bump and under adj ball adj metal and passivation and reflow\$3 and contact adj20 pad	DERWENT USPAT; EPO; JPO;	2003/09/01 17:21
-	0	solder adj20 pad solder adj20 bump and under adj ball adj metal and passivation and contact adj20 pad	DERWENT USPAT; EPO; JPO;	2003/09/01 17:21
-	0	pad solder and under adj ball adj metal and passivation and contact adj20 pad	DERWENT; USPAT; EPO; JPO;	2003/09/01 17:22
-	0	solder and under adj ball adj metal and passivation and contact adj pad	DERWENT USPAT; EPO; JPO;	2003/09/01 17:22
_	23	solder and UBM and passivation and contact adj pad	DERWENT USPAT; EPO; JPO; DERWENT	2003/09/01 17:22
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